

IN THE CLAIMS:

Please cancel claims 47 and 53-59 without prejudice and amend the claims as follows:

1-45. (Cancelled).

46. (Currently Amended) A method for electroplating a metal onto a substrate plating surface, comprising:

positioning the substrate plating surface face-up on a substrate support member;

positioning the support member at a first vertical position in a processing cell;

flowing an electroplating solution onto the substrate plating surface while rotating the substrate plating surface at the first vertical position;

electroplating the metal on the substrate plating surface by applying a plating bias to the substrate;

~~capturing the electroplating solution used in the electroplating process with a first fluid receiving member peripheral catch cup positioned about a perimeter of the substrate support member;~~

positioning the support member at a second vertical position in the processing cell;

rinsing the substrate plating surface with by flowing a rinsing agent to the substrate while rotating the substrate at the second vertical position; and

capturing the rinsing agent with a second fluid receiving member peripheral catch cup positioned about a perimeter of the substrate support member.

47. (Cancelled)

48. (Currently Amended) The method of claim 46, further comprising vibrating the substrate during the flowing of the electroplating solution.

49. (Previously Presented) The method of claim 46, further comprising providing a peripheral seal between the substrate support member and a back side of the substrate.

50. (Currently Amended) The method of claim 46, further comprising purifying the rinsing agent captured by the second ~~fluid receiving member~~ peripheral catch cup.

51. (Currently Amended) The method of claim 46, further wherein applying the plating bias comprises comprising applying a the plating bias between the substrate plating surface and an anode positioned above the substrate plating surface.

52. (Previously Presented) The method of claim 46, further comprising spin-drying the substrate.

53 – 59. (Cancelled).

60. (Withdrawn) A method for plating a metal onto a substrate, comprising:
positioning the substrate on a substrate support member, wherein a plating surface of the substrate is facing up;
positioning the substrate at a first vertical position;
flowing a plating solution to the plating surface of the substrate while rotating the substrate at the first vertical position;
capturing the plating solution with a first catch cup ;
positioning the substrate at a second vertical position;
flowing a rinsing agent to the plating surface of the substrate while rotating the substrate at the second vertical position; and
capturing the rinsing agent with a second catch cup.

61. (Withdrawn) The method of claim 60, wherein the first and second catch cups are disposed about a perimeter of the substrate support member.

62. (Withdrawn) The method of claim 60, further comprising vibrating the substrate during flowing the plating solution.

63. (Withdrawn) The method of claim 60, further comprising purifying the captured rinsing agent.

64. (Withdrawn) The method of claim 60, further comprising providing a peripheral seal between the substrate support member and a back side of the substrate.

65. (Withdrawn) The method of claim 64, further comprising providing a fluid flow directed at the back side of the substrate.